



BURST

Breaking Limits Using Record Enabling Silicon Technology With Photonic Management

SMARTIES cluster workshop

03/06/2026

Front side texturing strategies for BC solar cells in the BURST project

Laurent CLOCHARD

NINES PHOTOVOLTAICS



Nines
Photovoltaics



BURST: Breaking Limits Using Record
Enabling Silicon Technology With Photonic
Management

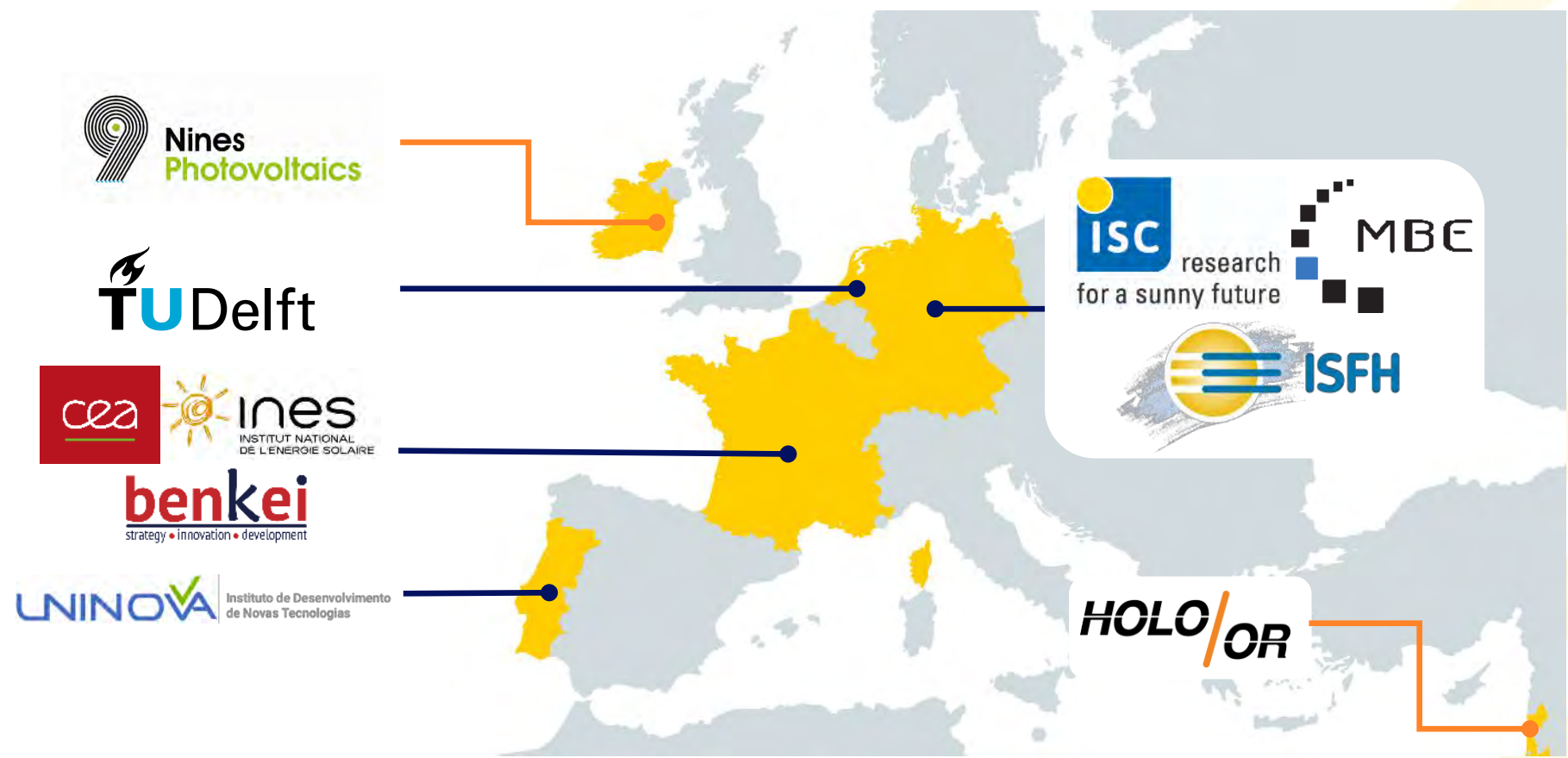


Funded by
the European Union



Partners

Gathering expertise from across Europe

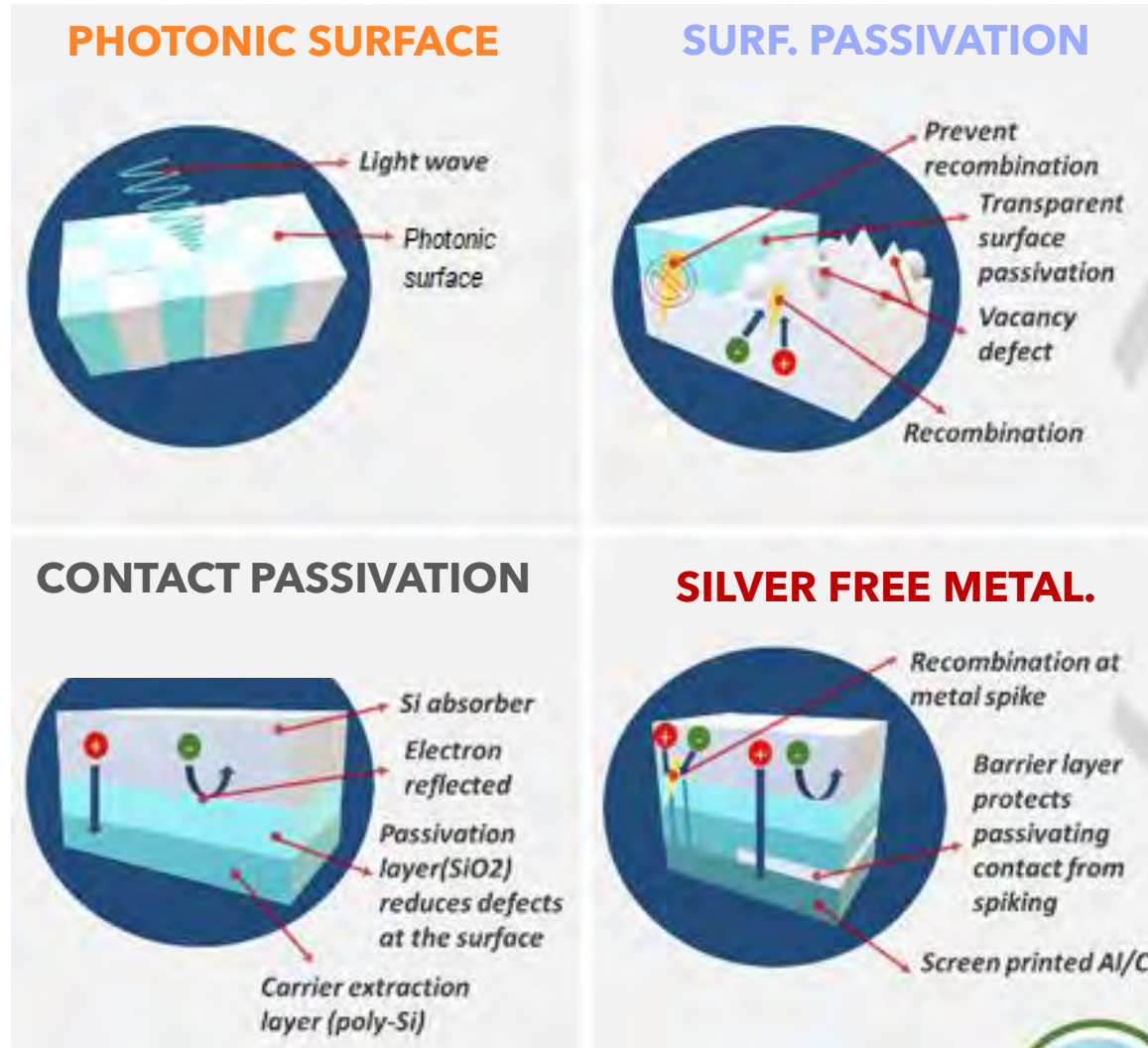


Timeline: 2 out of 3 years



The BURST project has received funding from the European Union's Horizon Europe research and innovation programme under grant agreement No 101146684

TECHNOLOGICAL BUILDING BLOCKS



- ◆ 4 main areas
- ◆ TRL 4/5



BURST ambition

Efficiency targets of

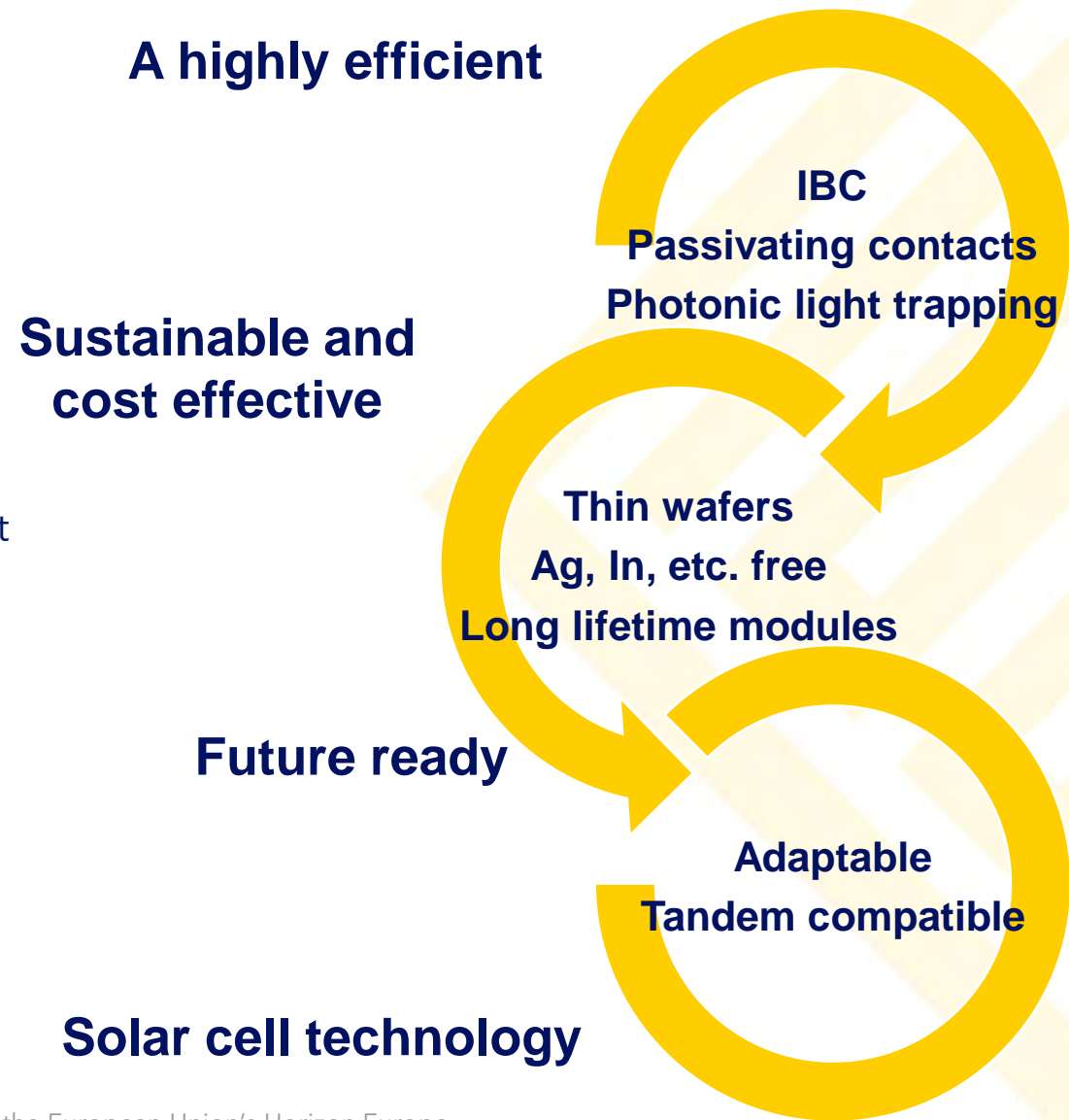
- ◆ 27% on 300 μm thick solar cells
- ◆ 26% on 80 μm thin solar cells

Industrial viability

- ◆ All processes compatible with high throughput tools

Flexible applicability

- ◆ Most developments suitable for Si bottom cell
- ◆ Most developments compatible with TOPCon





Overview of investigated light trapping schemes



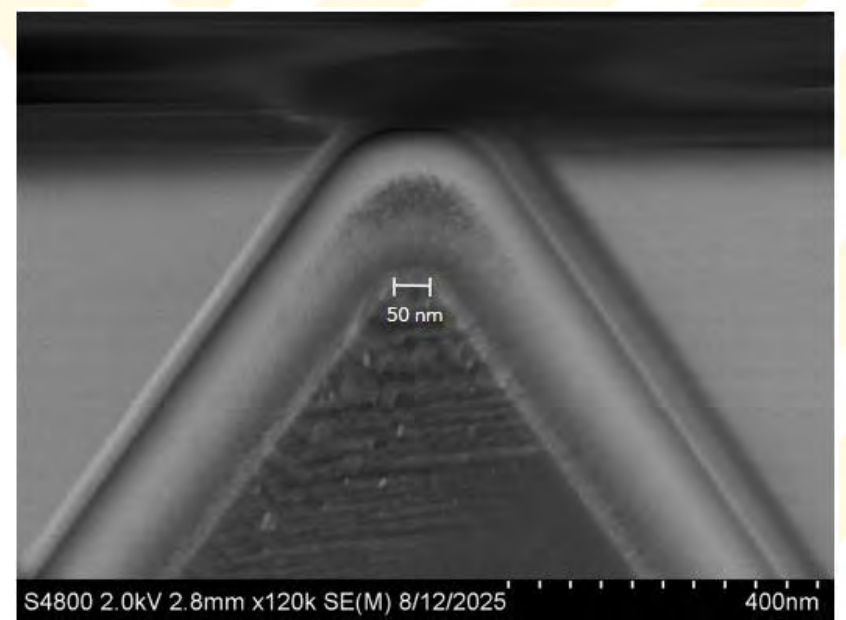
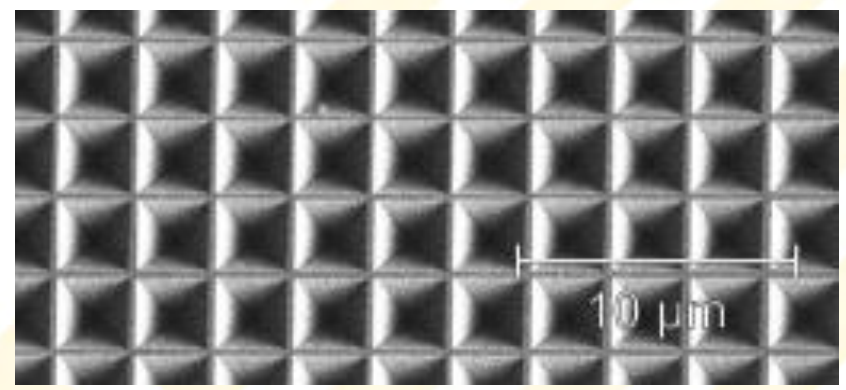
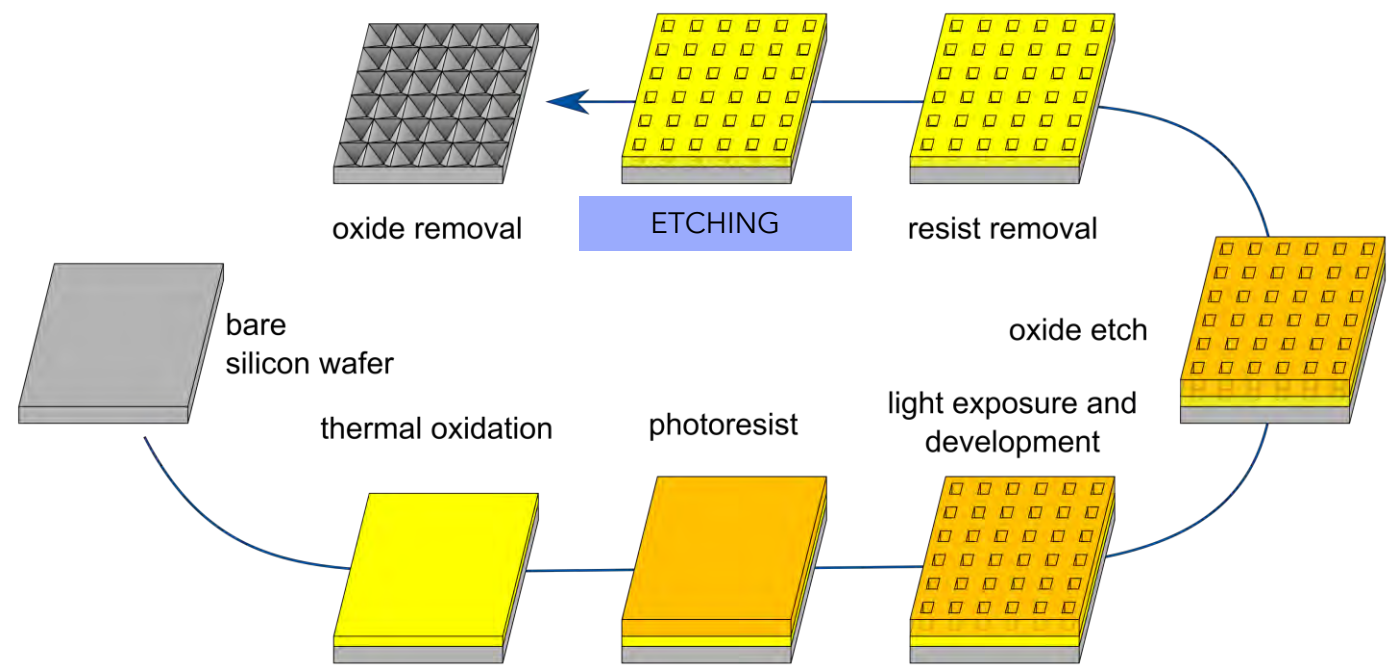
Type of Structure	Masking method	Pattern transfer	Structure obtained
PERIODIC	Std. lithography	Wet-chemical etching	Inverted pyramids
		RIE + wet-chemical etching	
	Colloidal lithography	ADE gas-phase etching	Inverted domes
		TiO2 infiltration	
		ADE gas-phase etching	exploratory
		Split beam Laser opening	Wet-chemical
ADE gas-phase etching	Inverted domes		
RANDOM	-	RIE Plasma etching	Nano-texture
		SiO2 etched	
	ADE gas-phase etching		
	-	KOH pyramids + ADE	
MIXED	-	Inverted pyramids + ADE	Micro + Nano
	-	Inverted pyramids + SiO2 etch	





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	Colloidal lithography	ADE gas-phase etching	exploratory
		Laser opening	Wet-chemical
ADE gas-phase etching	Inverted domes		

➔ STRUCTURED scheme aims to investigate potential effects from photonic crystals





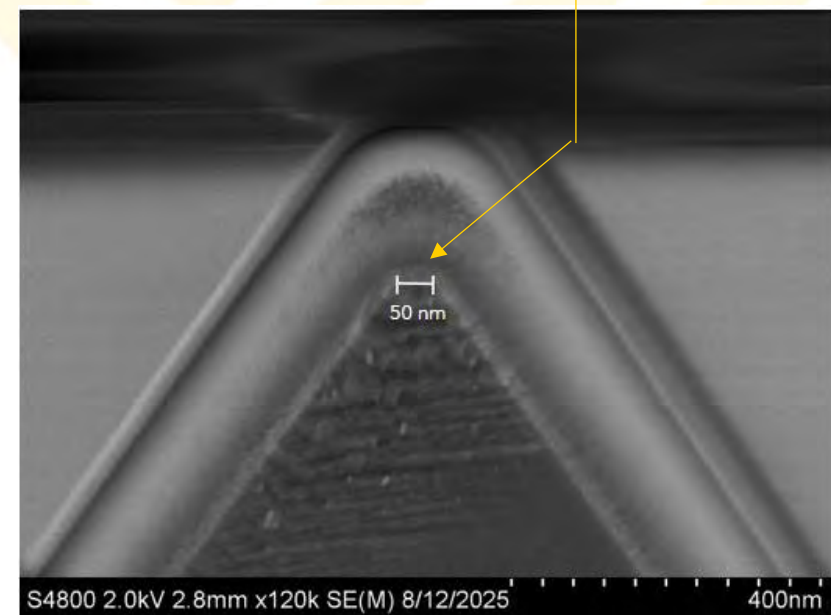
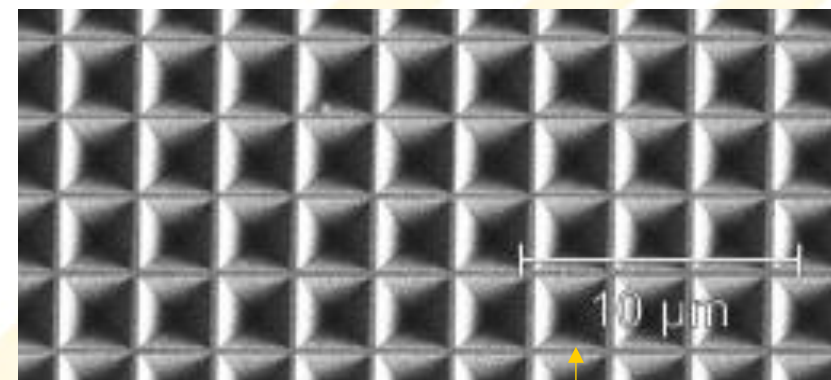
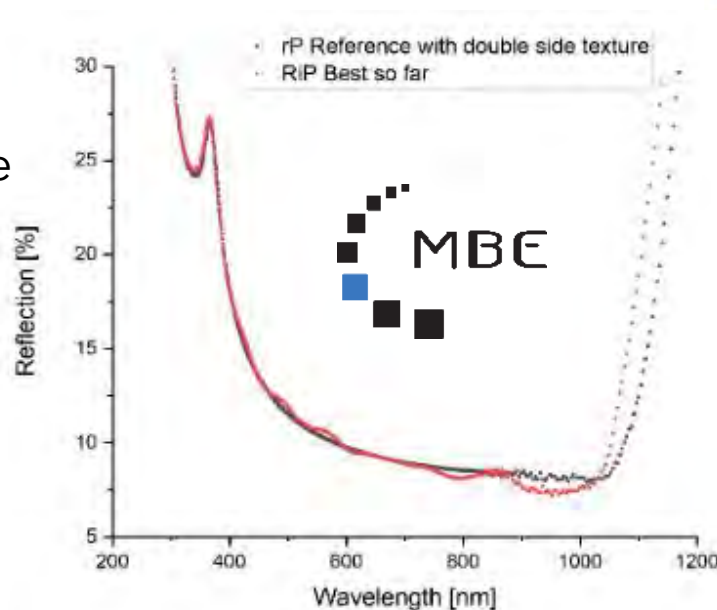
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	Colloidal lithography	ADE gas-phase etching	exploratory
		Laser opening	Wet-chemical
ADE gas-phase etching	Inverted domes		

Main challenge:

➔ Minimizing the flat edges between inverted pyramids (highly reflective)

Best reflectivity so far:

➔ Close match to alkaline reference












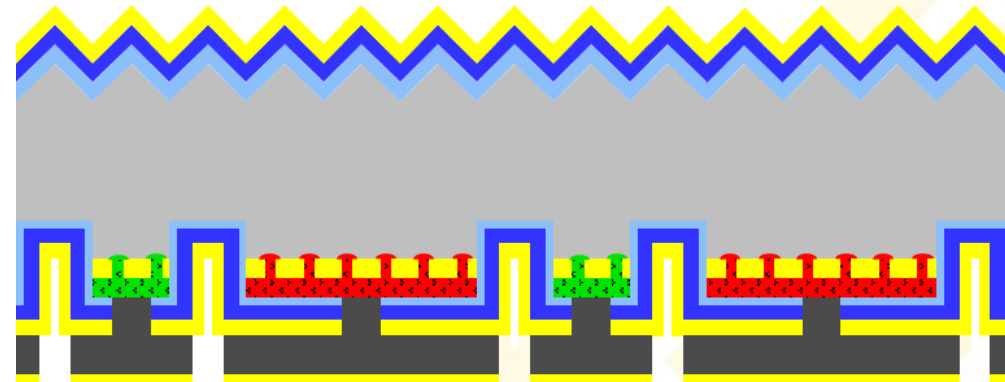
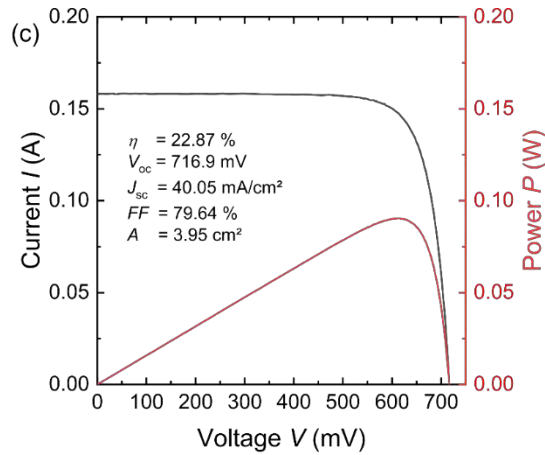
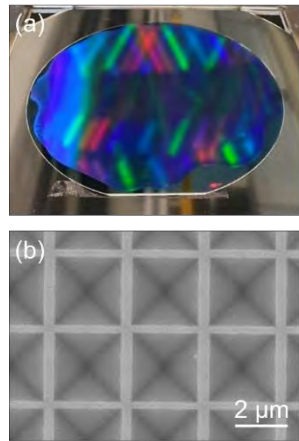
IMPLEMENTATION INTO SOLAR CELLS

Inverted pyramids with a pitch of 3.1 μm in POLO²-IBC solar cells



Legend

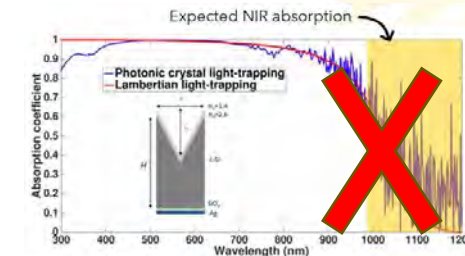
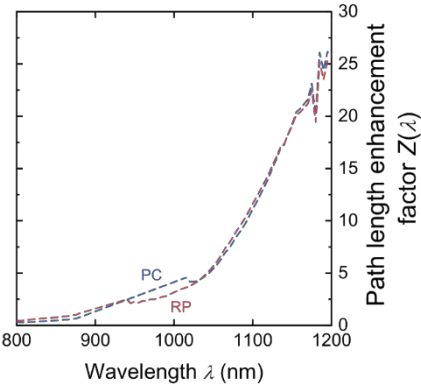
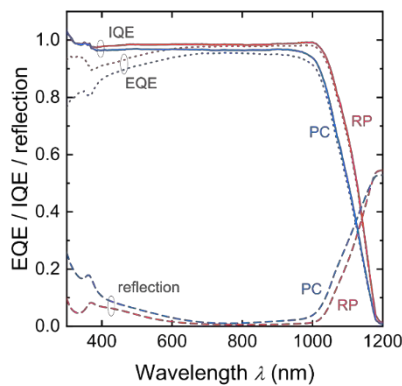
-  p-Si
-  n⁺-Si
-  p⁺-Si
-  SiN_x
-  Al₂O₃
-  SiO₂
-  Al



Main conclusion:

No evidence of increased absorption in the IR

- ➔ Correlates with advanced simulations carried out within this project
- ➔ No “photonic crystal” effect at long wavelength range



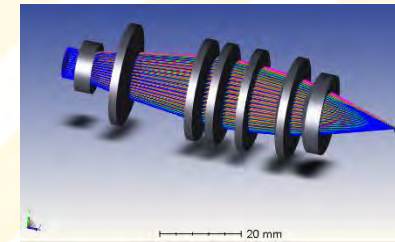
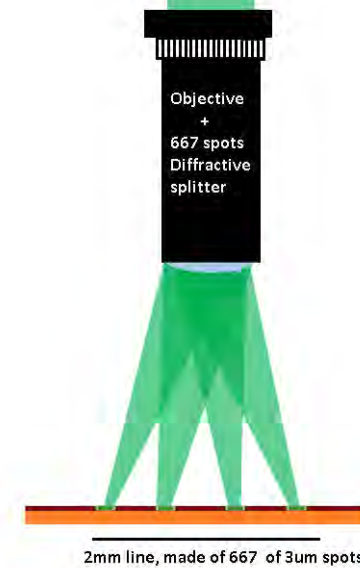
S. Bhattacharya, S. John, Scientific Reports, 2019



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		Laser opening	Wet-chemical
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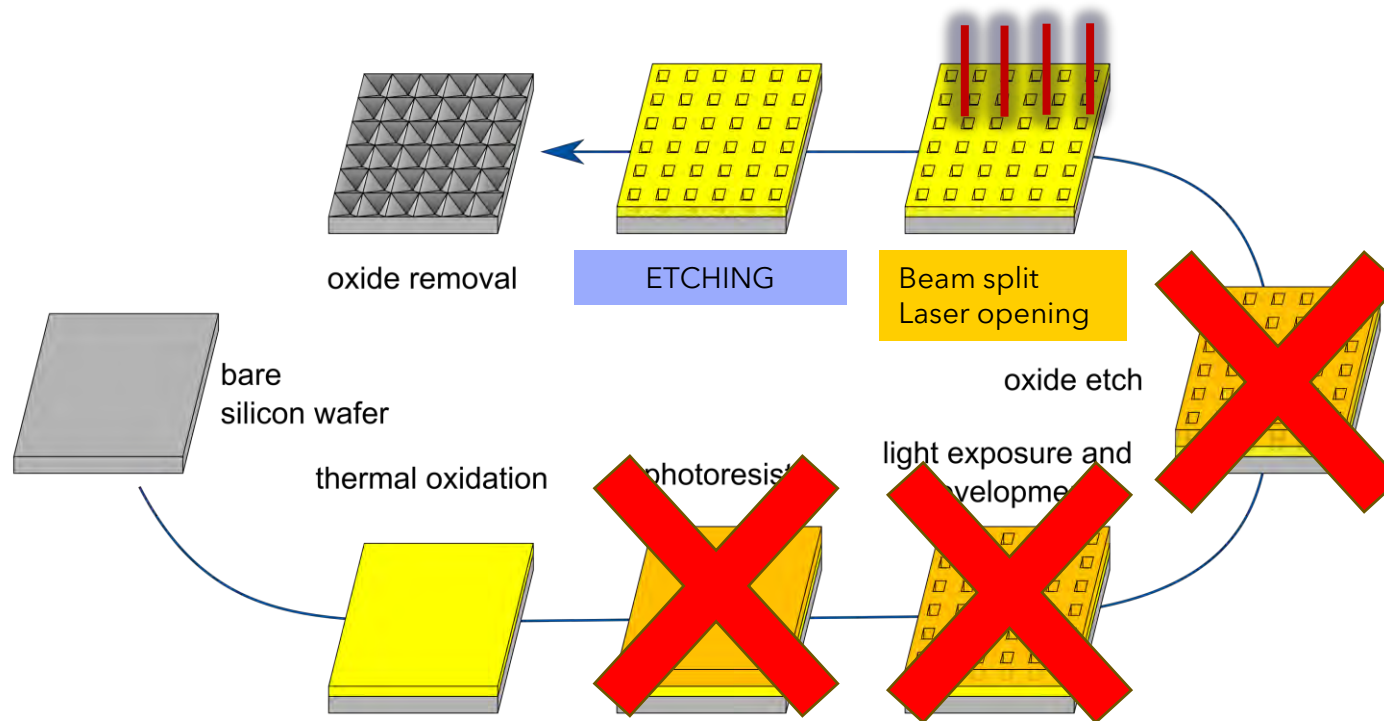
Development of a beam splitter

HOLO/OR

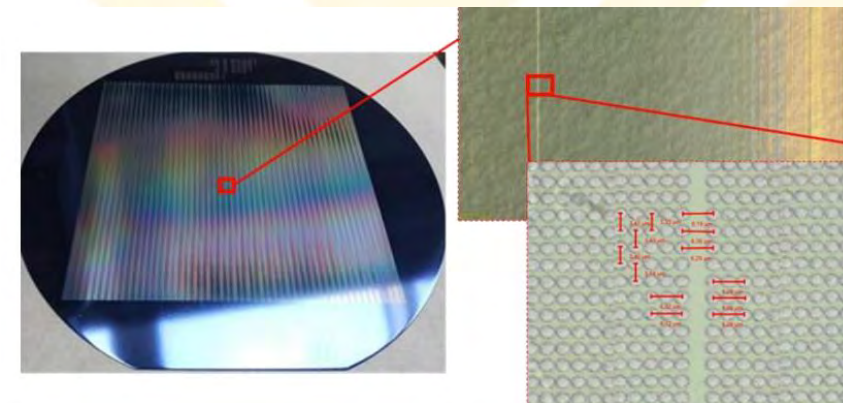


2mm line, made of 667 of 3um spots,

Single module: 2mm lines, made of 667 x 3um spots

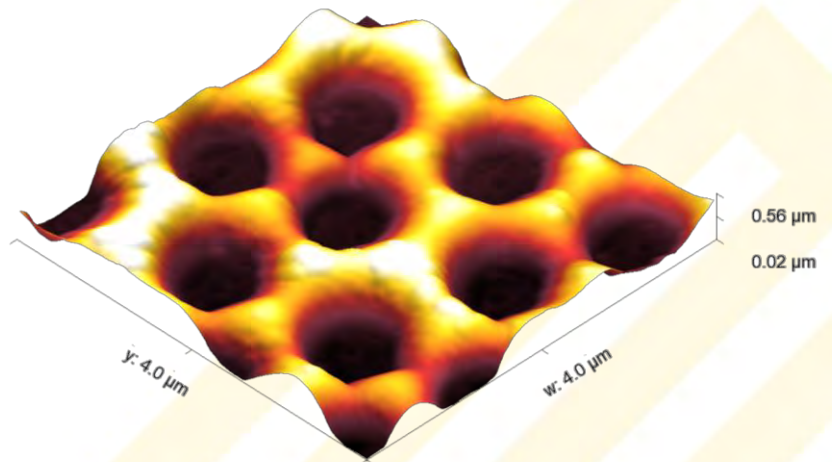


➔ Removes Steps from standard litho. process





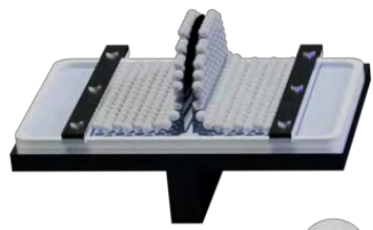
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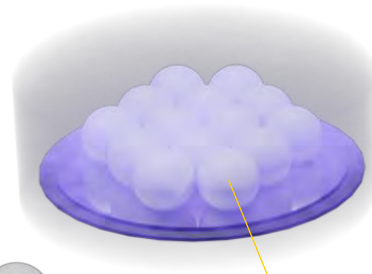
TiO₂ voids



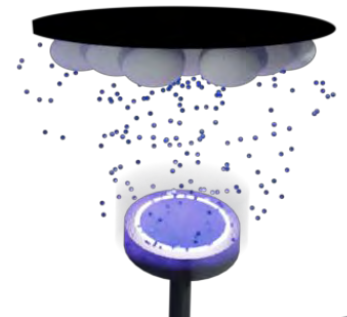
1. Langmuir-Blodgett



2. O₂ RIE



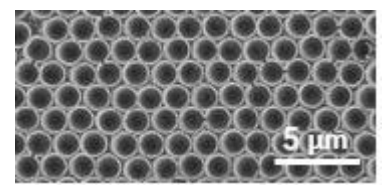
3. TiO₂ Infiltration



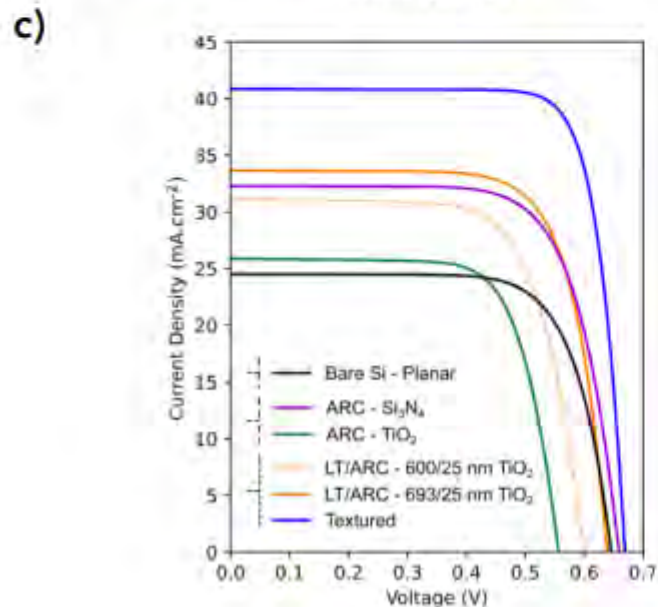
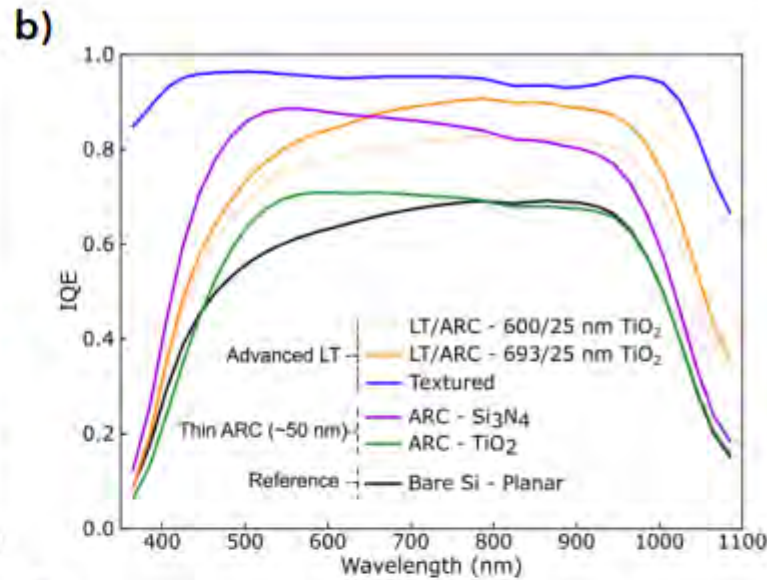
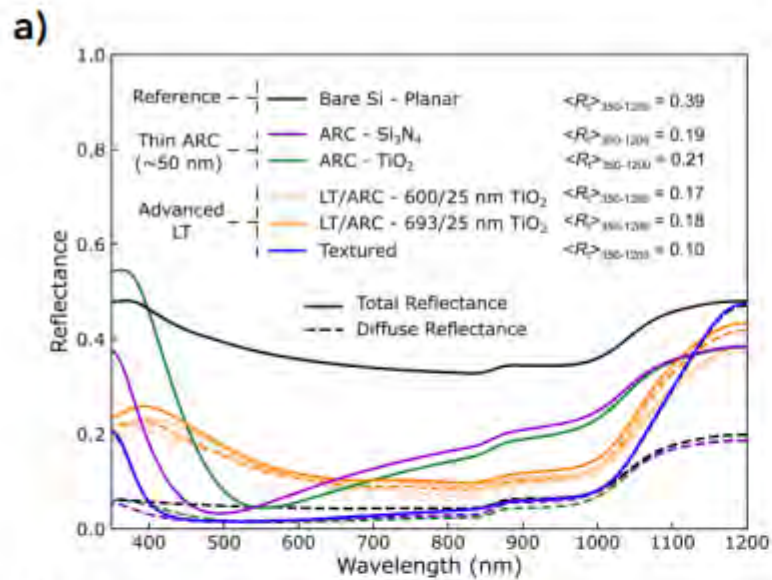
4. Lift-off



2-3um Polystyrene spheres

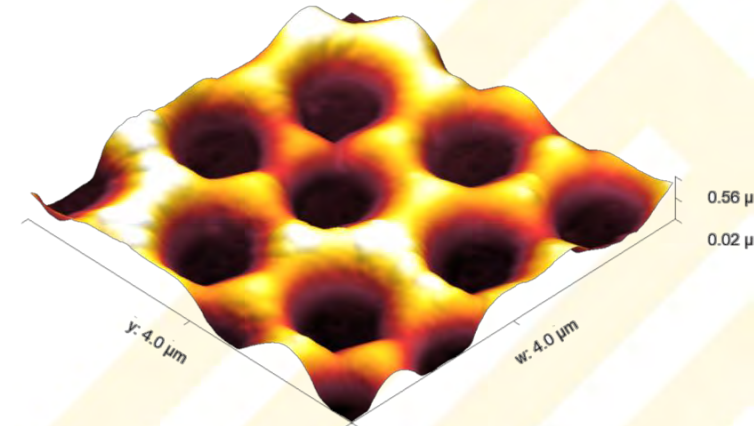


➔ Added layer (TiO₂) is structured to lower the flat surface reflection



d)

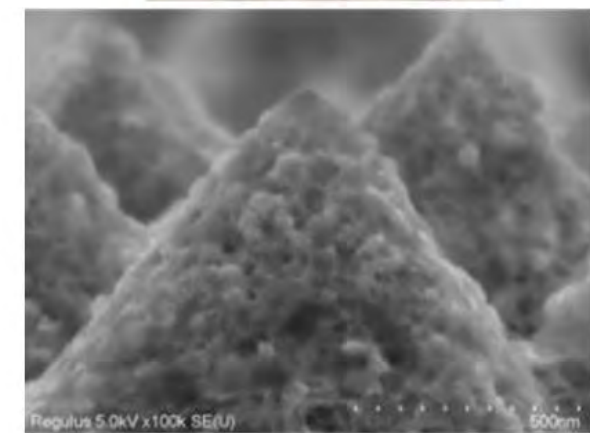
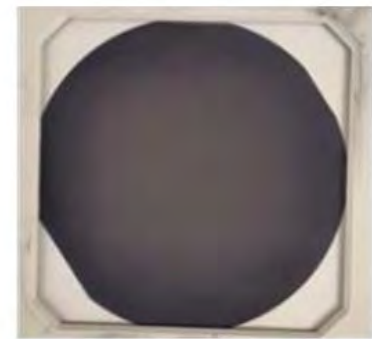
Sample	V_{oc} (mV)	J_{sc} (mA.cm ⁻²)	FF (%)	PCE (%)
Bare Si - Planar	646	24.5	72.9	11.5
ARC - SiN	659	32.3	71.5	15.2
ARC - TiO ₂	556	25.9	72.4	10.4
LT/ARC 600/25 nm	599	31.1	69.9	13.0
LT/ARC 693/25 nm	638	33.7	73.3	15.8
Textured	669	40.8	79.4	21.7



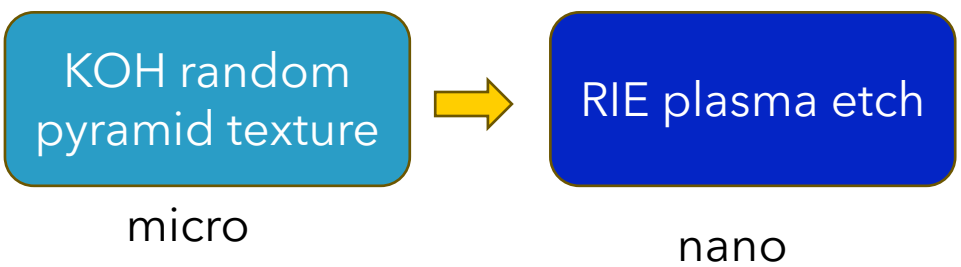
➔ Reflectivity reduction compared to flat Surface
 ➔ Useful for ultra thin wafers
 Next: work on index matching & passivation



Type of Scheme	Masking method	Pattern transfer	Structure obtained
RANDOM	-	RIE Plasma etching	Nano-texture
		SiO2 etched	
	ADE gas-phase etching		
MIXED	-	KOH pyramids + ADE	Micro + Nano
	-	Inverted pyramids + ADE	
	-	Inverted pyramids + SiO2 etch	

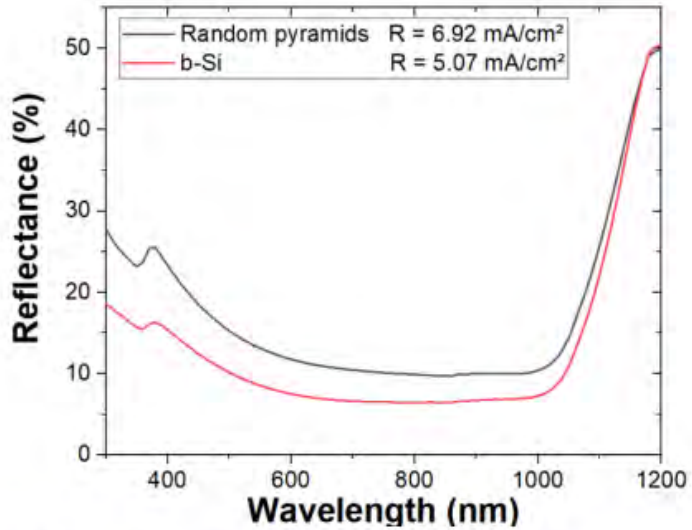


Random nano-micro texturing for light in-coupling:

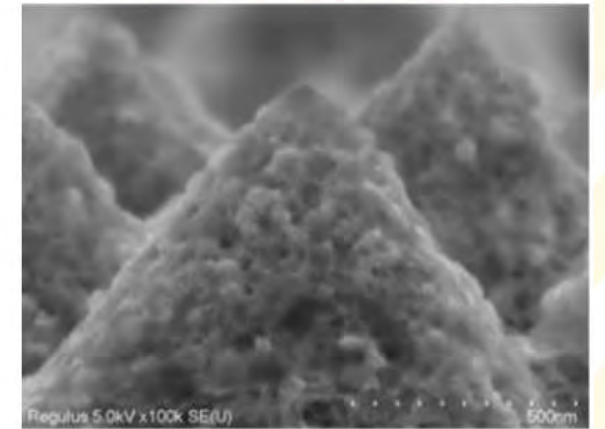


- room temperature plasma process employing fluorine/oxygen/argon chemistry.





Reflection curves of M2 wafers with random pyramid texture and b-Si after a-Si:H deposition by PECVD.

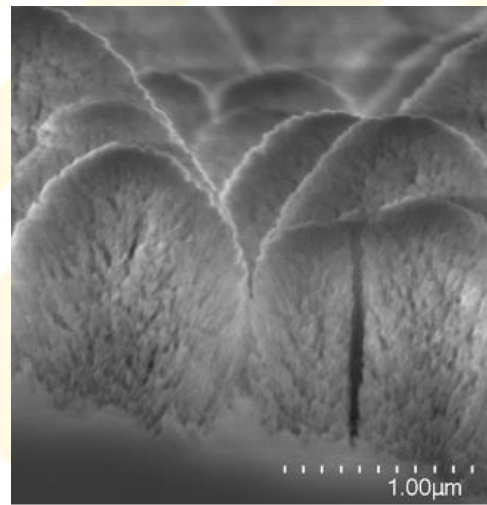


 **TU Delft**

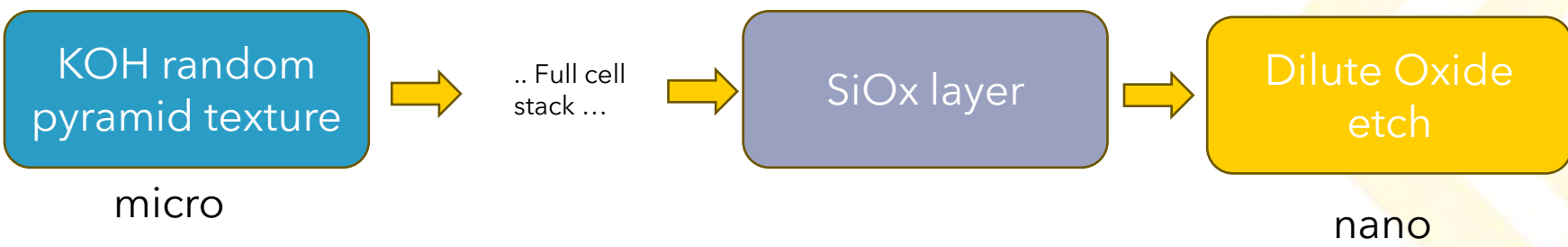
- Preliminary tests executed on symmetric M2-sized c-Si wafers passivated with 20-nm thick ALD AlO_x
 - $\tau_{\text{eff}} \sim 5 \text{ ms}$ ($\Delta n = 1 \times 10^{15} \text{ cm}^{-3}$) and $i\text{-}V_{\text{OC}} > 735 \text{ mV}$
- ➔ Can be passivated with ALD AlO_x



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	-	Inverted pyramids + SiO ₂ etch	

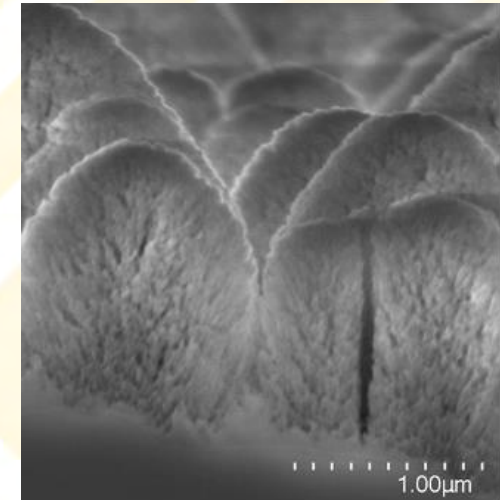
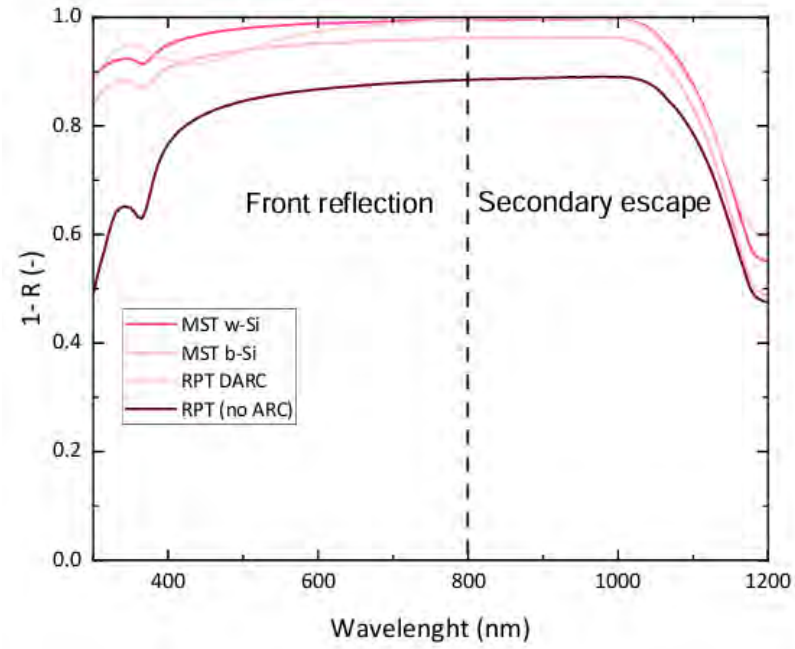
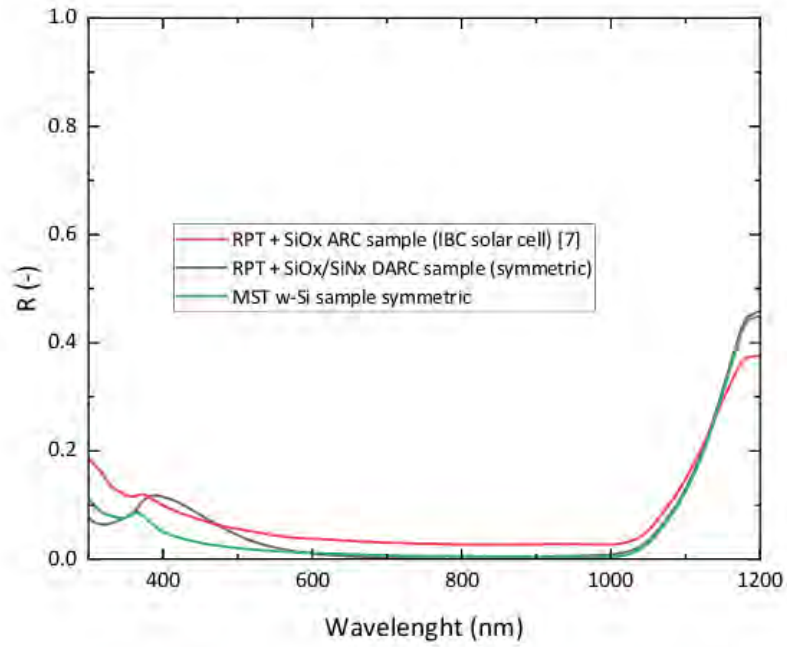


Random nano-micro texturing for light in-coupling:



- Additional optical layer
- does not affect existing passivation





➔ Very low reflectivity potential

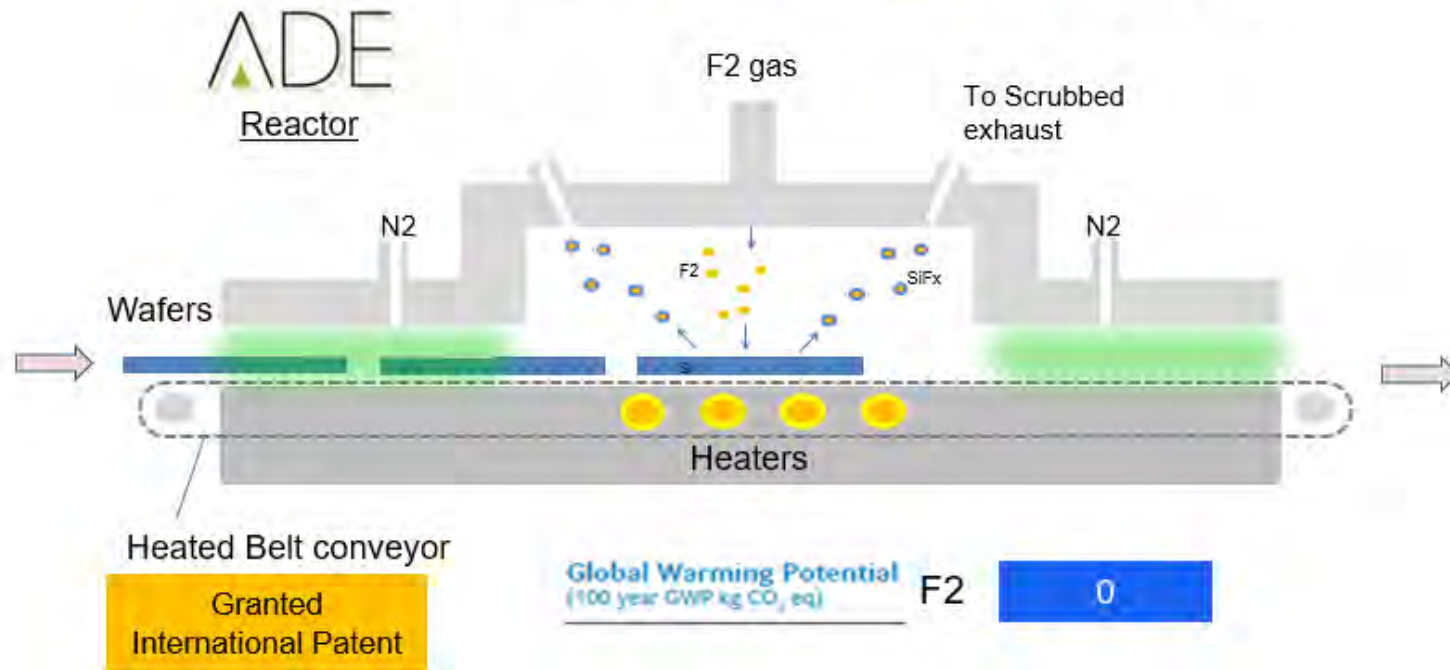


Overview: ADE gas-phase etch applications

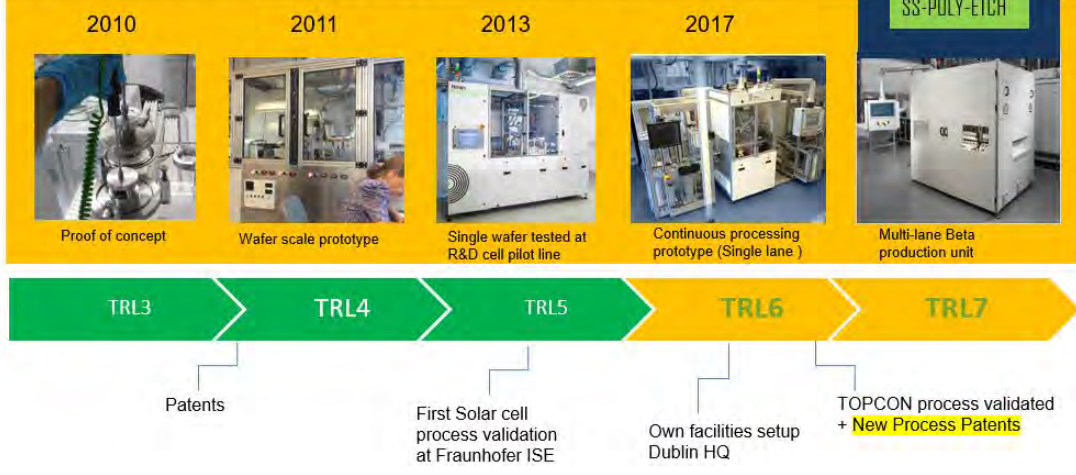
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	-	KOH pyramids + ADE	
MIXED	-	Inverted pyramids + ADE	Micro + Nano
	-	Inverted pyramids + SiO2 etch	

WHAT IS ADE gas-phase etching?

- **Thermal** process using molecular Fluorine **gas** (F₂)
- Low temperature **Chemical etching** (NO PLASMA / IONS)
- **Atmospheric** pressure process (no vacuum)
- **In-line** tool layout with **continuous** flow of wafers



DEVELOPMENT OF GAS-PHASE ETCHING



- Low COO process
- Ultra high throughput

ADE multi-GW PRODUCTION TOOLS → Poly-Si removal



Efficiency = smaller tools, faster processing

Wet Batch Tool
20 meters long
10,000 wafers per hour

- X-Large Water footprint
- Massive m² Tools - ~1/3 of factory
- Power HUNGRY ! > 300 kW /GW
- Large CO₂ footprint from tool & HVAC

ADE SS-POLY-ETCH
2 meters long
24,000 wafers per hour

- HALF the cost Lower power consumption
- Smaller, faster, cheaper
- Ultra-high etch rate 10x

M10 etching tool throughput trend (wafer per hour)

Year	Wet Batch	Wet Inline	ADE
2023	~12,000	~10,000	~20,000
2025	~13,000	~11,000	~25,000
2027	~14,000	~12,000	~30,000
2029	~15,000	~13,000	~35,000
2031	~16,000	~14,000	~40,000

BURST project presentation



The BURST project has received funding from the European Union's Horizon Europe research and innovation programme under grant agreement No 101146684



Relevance:

- Single side etching
- Selective
- High throughput

Under specific conditions:

- Nano-texturing

Single side & selective : leverage for **patterning**

- Etch **rate** is the speed of the etching process for a material [nm/min]
- Etch **selectivity** is the ratio of etch rates between materials

$$S = E_x / E_{C-Si}$$

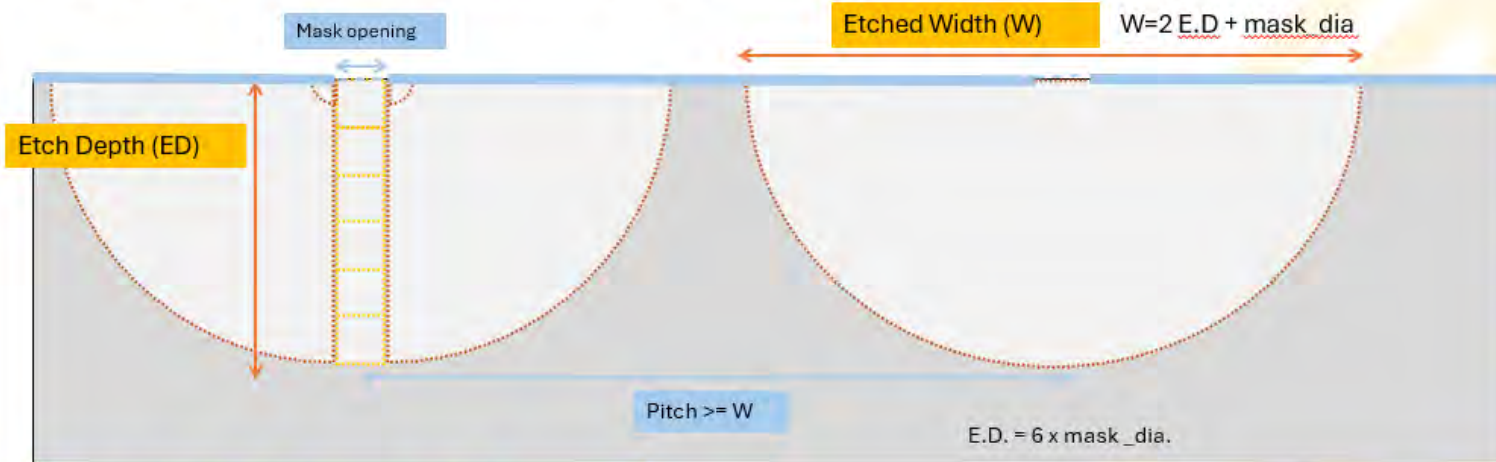
Material	Etch rate [nm/min]	Selectivity vs. c-Si
n-type c-Si	Reference	1:1
n-poly Si	1:1	1:1
i-poly Si	1.4:1	1.4:1
Boron emitter	1.6.5	1.6.5:1
p-poly Si (activated)	1:11	1:11
SiN _x	1:200	1:200
SiC	1:1950	1:1950
BSG	1:2000	1:2000
Thermal oxide	1:2000	1:2000

Patent pending

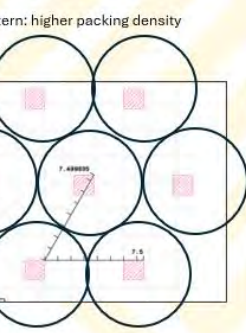
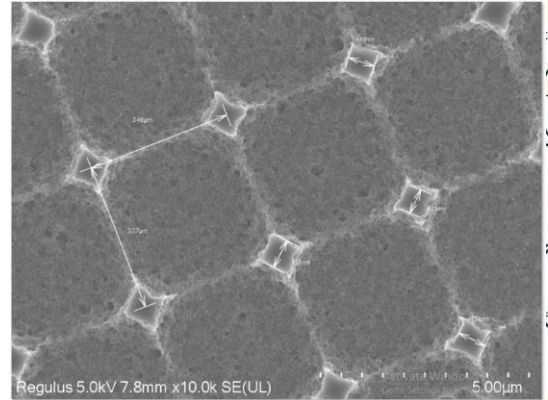
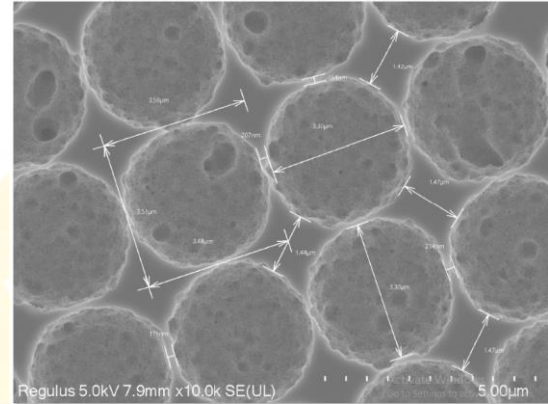
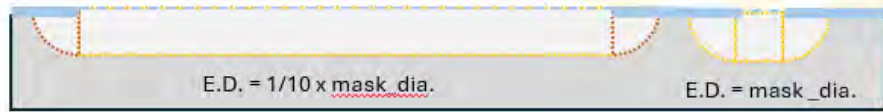


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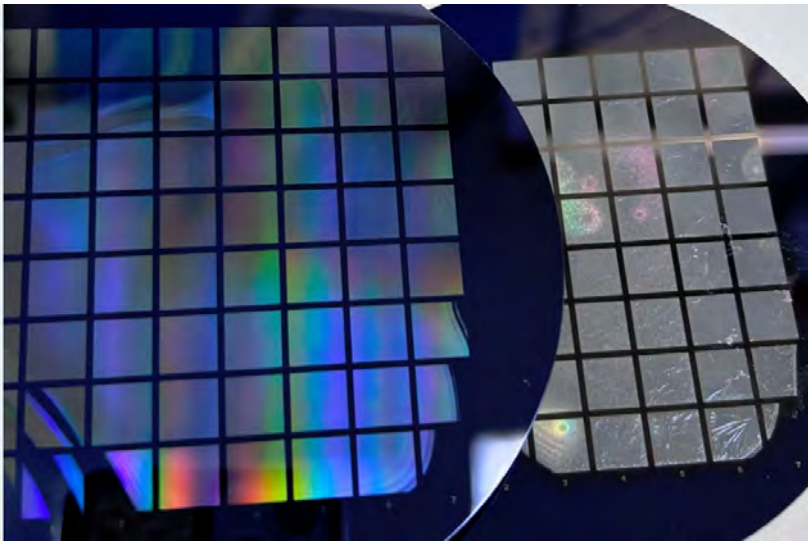
ISOTROPIC ETCH: equal etch in all directions



Minimum Pitch required: Pitch >= W
 Max Aspect ratio: ED/W <= 0.5 Max



- ➔ Limited aspect ratio
- ➔ Sensitive to contamination



Before

After

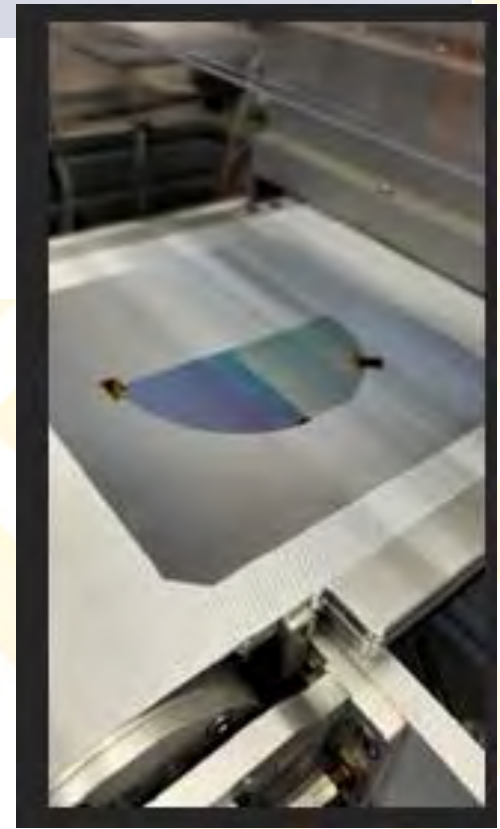
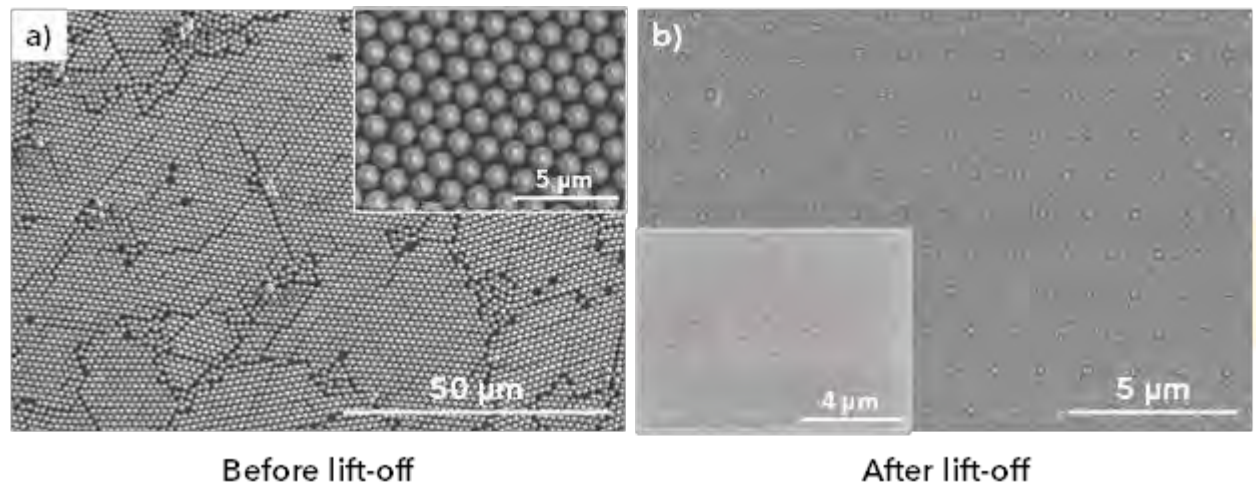
Over-etched samples → SiO_x film is preserved





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	Colloidal lithography		exploratory
	Laser opening		

- Using polystyrene spheres as a mask within ADE etching



- Sphere can withstand ADE process (at low temperature)
- "Spot etching" very localised at point of contact
- On-going development to improve optical surface property

Overview: ADE gas-phase etch applications

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	Colloidal lithography		exploratory
	Laser opening		Inverted domes
RANDOM	-	ADE gas-phase etching	Micro + Nano
	-	KOH pyramids + ADE	
MIXED	-	Inverted pyramids + ADE	

Main Focus for the rest of the project



CONCLUSION

- Multiple approaches to front surface reflection being investigated
- Periodic structures have not shown clear optical advantages
- Double-texture (micro+nano) approach now most promising option
- Alternative to litho process being developed using high throughput tools (laser split beam + ADE)

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